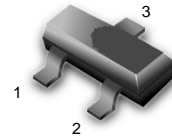


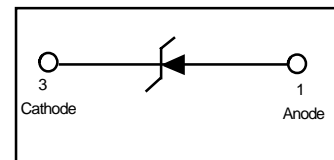
- We declare that the material of product compliance with RoHS requirements.
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable



SOT- 23 (TO-236AB)
PLASTIC

MAXIMUM CASE TEMPERATURE FOR SOLDERING

PURPOSES: 260°C for 10 seconds



THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR-5 Board(Note 1) $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	225	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	556	$^\circ\text{C/W}$
Total Device Dissipation Alumina Substrate (Note 2), $T_A = 25^\circ\text{C}$ Derate above 25°C	P_D	300	mW
Thermal Resistance Junction to Ambient	$R_{\theta JA}$	417	$^\circ\text{C/W}$
Junction and Storage Temperature	T_J, T_{stg}	-55to+150	$^\circ\text{C}$

Note 1. FR-5 = 1.0 x 0.75 x 0.62 in.

Note 2. Alumina = 0.4 x 0.3 x 0.024 in. 99.5% alumina.

Ordering Information

Device	Package	Shipping
BZX84C2V4LT1G Series	SOT-23	3000/Tape&Reel
BZX84C2V4LT3G Series	SOT-23	10000/Tape&Reel

ELECTRICAL CHARACTERISTICS – BZX84CxxxLT1 SERIES (STANDARD TOLERANCE)

(Pinout: 1-Anode, 2-No Connection, 3-Cathode) ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.90\text{ V Max.}$ @ $I_F = 10\text{ mA}$)

Device*	Device Marking	V _{Z1} (Volts) @ I _{ZT1} = 5 mA (Note 3)			Z _{ZT1} (Ω) @ I _{ZT1} = 5 mA	V _{Z2} (V) @ I _{ZT2} = 1 mA (Note 3)		Z _{ZT2} (Ω) @ I _{ZT2} = 1 mA	V _{Z3} (V) @ I _{ZT3} = 20 mA (Note 3)		Z _{ZT3} (Ω) @ I _{ZT3} = 20 mA	Max Reverse Leakage Current		θ _{VZ} (mV/k) @ I _{ZT1} = 5 mA		C (pF) @ V _R = 0 f = 1 MHz
		Min	Nom	Max		Min	Max		Min	Max		I _R μA	V _R Volts	Min	Max	
BZX84C2V4LT1G	Z11	2.2	2.4	2.6	100	1.7	2.1	600	2.6	3.2	50	50	1	-3.5	0	450
BZX84C2V7LT1G	Z12	2.5	2.7	2.9	100	1.9	2.4	600	3	3.6	50	20	1	-3.5	0	450
BZX84C3V0LT1G	Z13	2.8	3	3.2	95	2.1	2.7	600	3.3	3.9	50	10	1	-3.5	0	450
BZX84C3V3LT1G	Z14	3.1	3.3	3.5	95	2.3	2.9	600	3.6	4.2	40	5	1	-3.5	0	450
BZX84C3V6LT1G	Z15	3.4	3.6	3.8	90	2.7	3.3	600	3.9	4.5	40	5	1	-3.5	0	450
BZX84C3V9LT1G	Z16	3.7	3.9	4.1	90	2.9	3.5	600	4.1	4.7	30	3	1	-3.5	-2.5	450
LBZX84C4V3LT1G	W9	4	4.3	4.6	90	3.3	4	600	4.4	5.1	30	3	1	-3.5	0	450
BZX84C4V7LT1G	Z1	4.4	4.7	5	80	3.7	4.7	500	4.5	5.4	15	3	2	-3.5	0.2	260
BZX84C5V1LT1G	Z2	4.8	5.1	5.4	60	4.2	5.3	480	5	5.9	15	2	2	-2.7	1.2	225
BZX84C5V6LT1G	Z3	5.2	5.6	6	40	4.8	6	400	5.2	6.3	10	1	2	-2.0	2.5	200
BZX84C6V2LT1G	Z4	5.8	6.2	6.6	10	5.6	6.6	150	5.8	6.8	6	3	4	0.4	3.7	185
BZX84C6V8LT1G	Z5	6.4	6.8	7.2	15	6.3	7.2	80	6.4	7.4	6	2	4	1.2	4.5	155
BZX84C7V5LT1G	Z6	7	7.5	7.9	15	6.9	7.9	80	7	8	6	1	5	2.5	5.3	140
BZX84C8V2LT1G	Z7	7.7	8.2	8.7	15	7.6	8.7	80	7.7	8.8	6	0.7	5	3.2	6.2	135
BZX84C9V1LT1G	Z8	8.5	9.1	9.6	15	8.4	9.6	100	8.5	9.7	8	0.5	6	3.8	7.0	130
BZX84C10LT1G	Z9	9.4	10	10.6	20	9.3	10.6	150	9.4	10.7	10	0.2	7	4.5	8.0	130
BZX84C11LT1G	Y1	10.4	11	11.6	20	10.2	11.6	150	10.4	11.8	10	0.1	8	5.4	9.0	130
BZX84C12LT1G	Y2	11.4	12	12.7	25	11.2	12.7	150	11.4	12.9	10	0.1	8	6.0	10.0	130
BZX84C13LT1G	Y3	12.4	13	14.1	30	12.3	14	170	12.5	14.2	15	0.1	8	7.0	11.0	120
BZX84C15LT1G	Y4	13.8	15	15.6	30	13.7	15.5	200	13.9	15.7	20	0.05	10.5	9.2	13.0	110
BZX84C16LT1G	Y5	15.3	16	17.1	40	15.2	17	200	15.4	17.2	20	0.05	11.2	10.4	14.0	105
BZX84C18LT1G	Y6	16.8	18	19.1	45	16.7	19	225	16.9	19.2	20	0.05	12.6	12.4	16.0	100
BZX84C20LT1G	Y7	18.8	20	21.2	55	18.7	21.1	225	18.9	21.4	20	0.05	14	14.4	18.0	85
BZX84C22LT1G	Y8	20.8	22	23.3	55	20.7	23.2	250	20.9	23.4	25	0.05	15.4	16.4	20.0	85
BZX84C24LT1G	Y9	22.8	24	25.6	70	22.7	25.5	250	22.9	25.7	25	0.05	16.8	18.4	22.0	80
Device	Device Marking	V _{Z1} Below @ I _{ZT1} = 2 mA			Z _{ZT1} Below @ I _{ZT1} = 2 mA	V _{Z2} Below @ I _{ZT2} = 0.1 m- A		Z _{ZT2} Below @ I _{ZT2} = 0.5 mA	V _{Z3} Below @ I _{ZT3} = 10 mA		Z _{ZT3} Below @ I _{ZT3} = 10 mA	Max Reverse Leakage Current		θ _{VZ} (mV/k) Below @ I _{ZT1} = 2 mA		C (pF) @ V _R = 0 f = 1 MHz
		Min	Nom	Max		Min	Max		Min	Max		I _R μA	V _R (V)	Min	Max	
BZX84C27LT1G	Y10	25.1	27	28.9	80	25	28.9	300	25.2	29.3	45	0.05	18.9	21.4	25.3	70
BZX84C30LT1G	Y11	28	30	32	80	27.8	32	300	28.1	32.4	50	0.05	21	24.4	29.4	70
BZX84C33LT1G	Y12	31	33	35	80	30.8	35	325	31.1	35.4	55	0.05	23.1	27.4	33.4	70
BZX84C36LT1G	Y13	34	36	38	90	33.8	38	350	34.1	38.4	60	0.05	25.2	30.4	37.4	70
BZX84C39LT1G	Y14	37	39	41	130	36.7	41	350	37.1	41.5	70	0.05	27.3	33.4	41.2	45
BZX84C43LT1G	Y15	40	43	46	150	39.7	46	375	40.1	46.5	80	0.05	30.1	37.6	46.6	40
BZX84C47LT1G	Y16	44	47	50	170	43.7	50	375	44.1	50.5	90	0.05	32.9	42.0	51.8	40
BZX84C51LT1G	Y17	48	51	54	180	47.6	54	400	48.1	54.6	100	0.05	35.7	46.6	57.2	40
BZX84C56LT1G	Y18	52	56	60	200	51.5	60	425	52.1	60.8	110	0.05	39.2	52.2	63.8	40
BZX84C62LT1G	Y19	58	62	66	215	57.4	66	450	58.2	67	120	0.05	43.4	58.8	71.6	35
BZX84C68LT1G	Y20	64	68	72	240	63.4	72	475	64.2	73.2	130	0.05	47.6	65.6	79.8	35
BZX84C75LT1G	Y21	70	75	79	255	69.4	79	500	70.3	80.2	140	0.05	52.5	73.4	88.6	35

Note 3. Zener voltage is measured with a pulse test current I_Z at an ambient temperature of 25°C .

TYPICAL CHARACTERISTICS

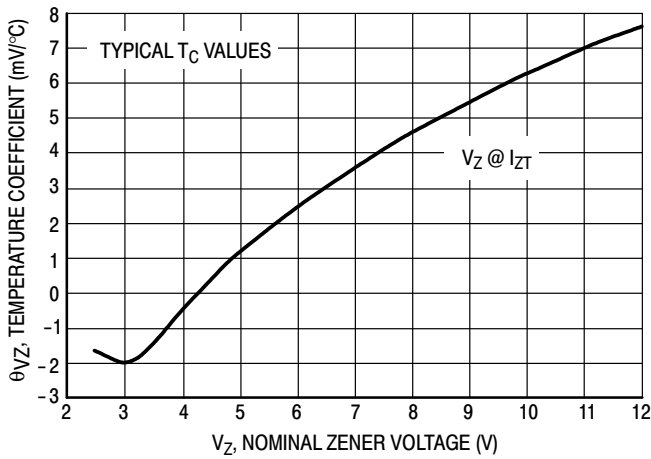


Figure 1. Temperature Coefficients
 (Temperature Range -55°C to +150°C)

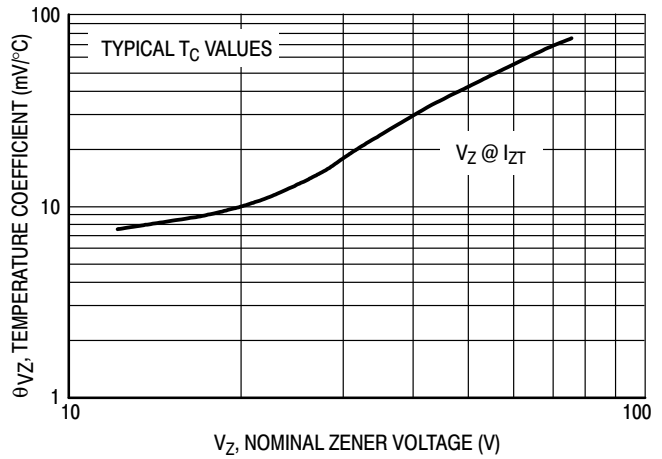


Figure 2. Temperature Coefficients
 (Temperature Range -55°C to +150°C)

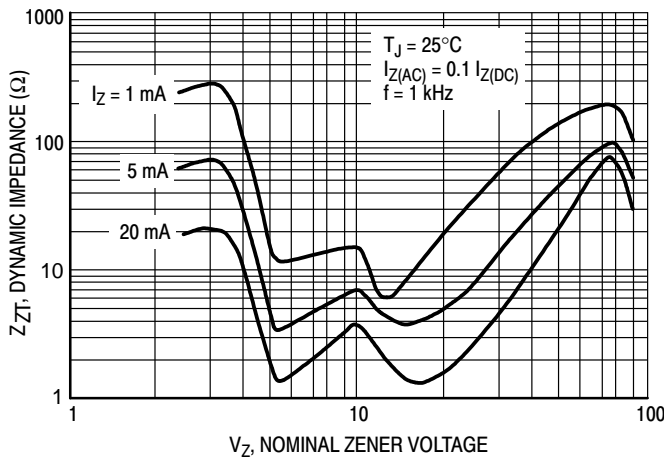


Figure 3. Effect of Zener Voltage on Zener Impedance

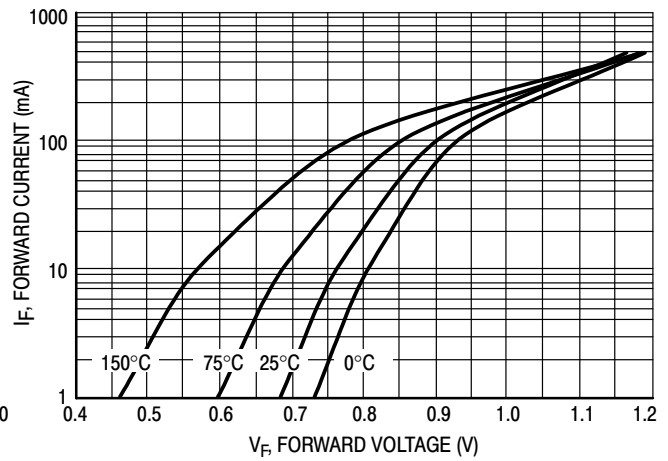


Figure 4. Typical Forward Voltage

TYPICAL CHARACTERISTICS

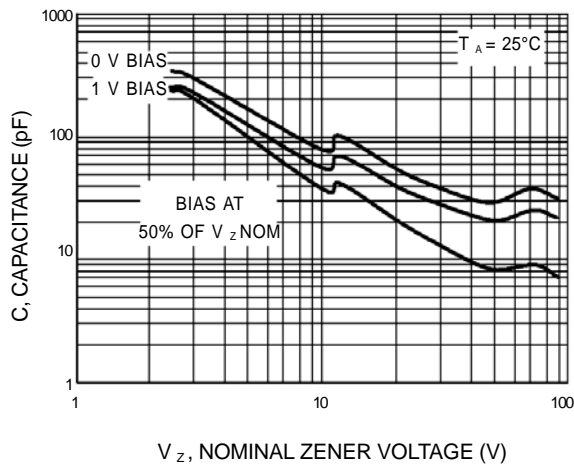


Figure 5. Typical Capacitance

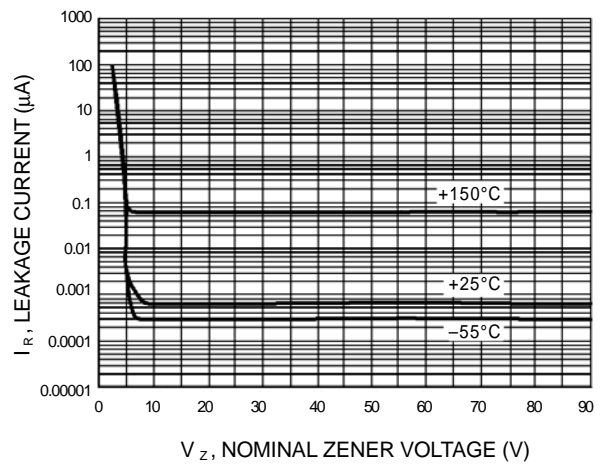


Figure 6. Typical Leakage Current

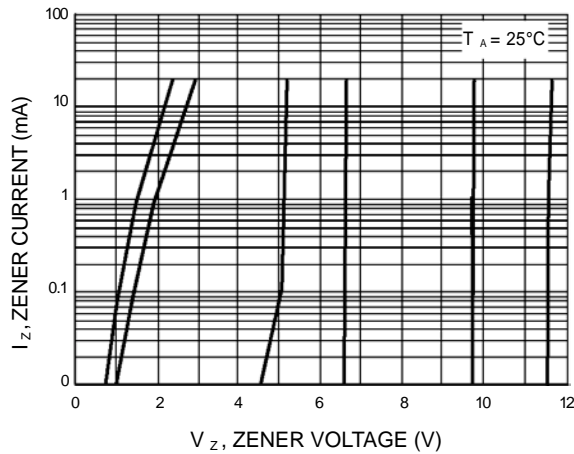


Figure 7. Zener Voltage versus Zener Current (V_z Up to 12 V)

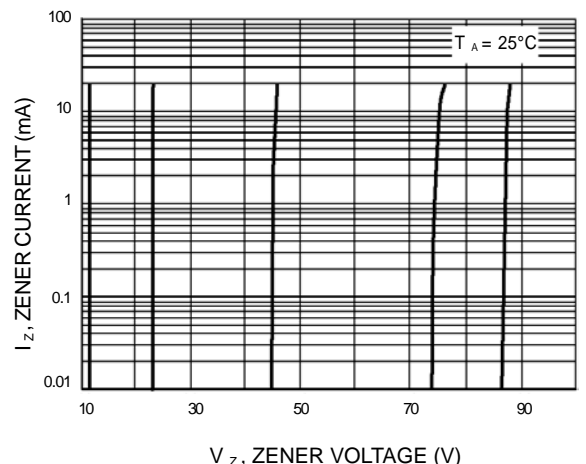
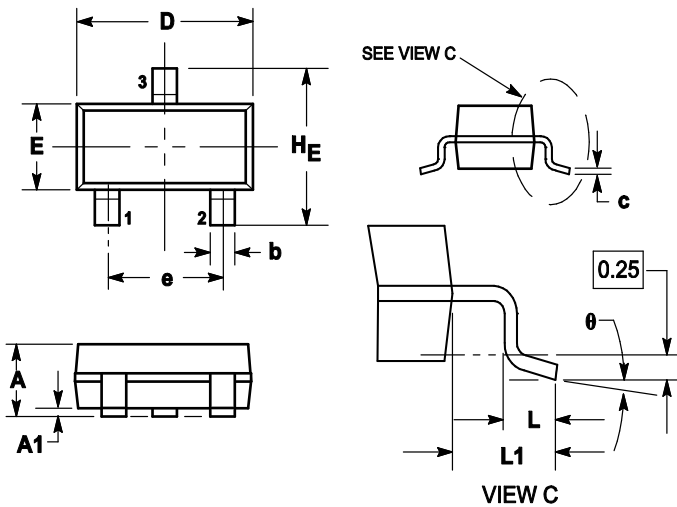


Figure 8. Zener Voltage versus Zener Current (12 V to 91 V)

OUTLINE AND DIMENSIONS



Notes:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.89	1	1.11	0.035	0.04	0.044
A1	0.01	0.06	0.1	0.001	0.002	0.004
b	0.37	0.44	0.5	0.015	0.018	0.02
c	0.09	0.13	0.18	0.003	0.005	0.007
D	2.80	2.9	3.04	0.11	0.114	0.12
E	1.20	1.3	1.4	0.047	0.051	0.055
e	1.78	1.9	2.04	0.07	0.075	0.081
L	0.10	0.2	0.3	0.004	0.008	0.012
L1	0.35	0.54	0.69	0.014	0.021	0.029
HE	2.10	2.4	2.64	0.083	0.094	0.104
θ	0°	---	10°	0°	---	10°

SOLDERING FOOTPRINT

